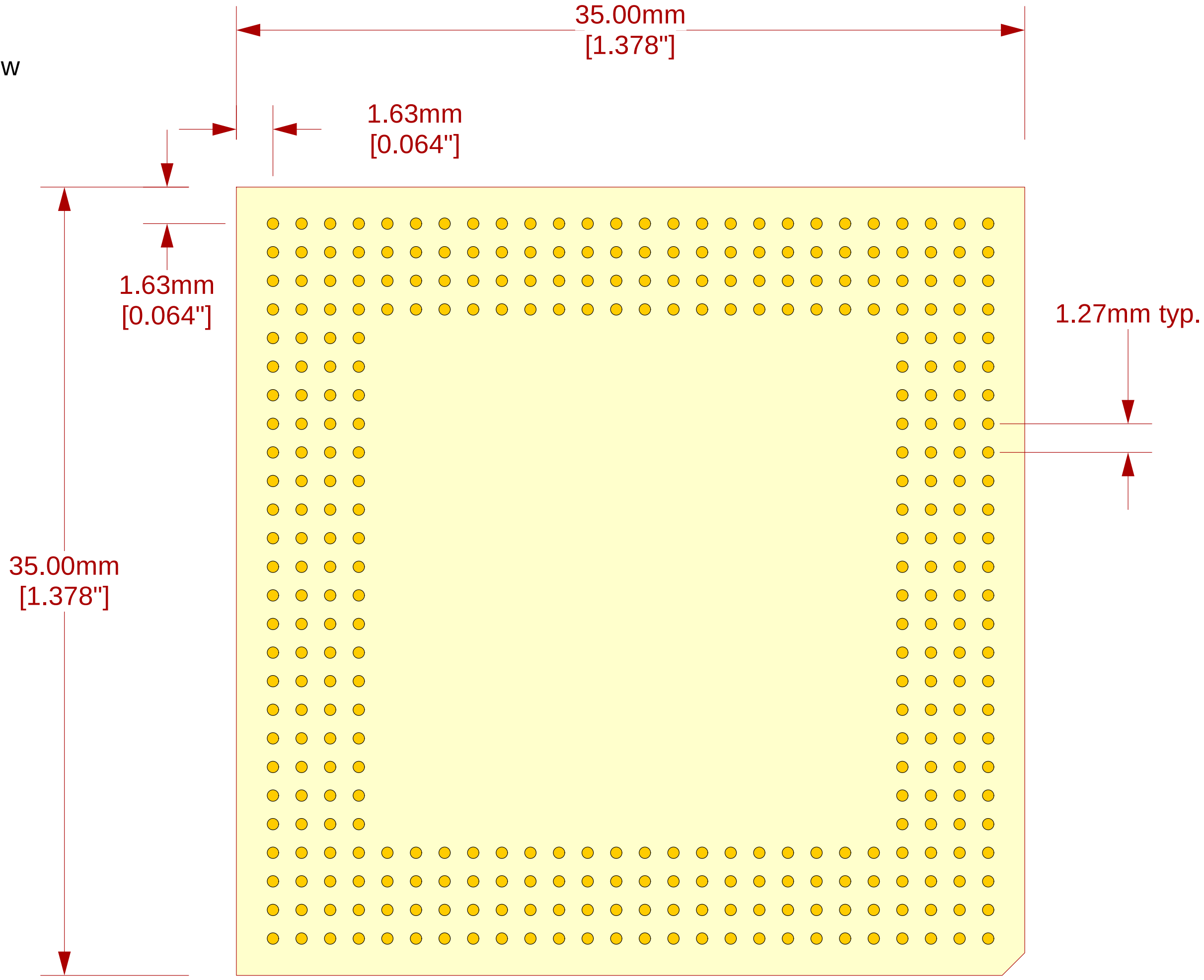
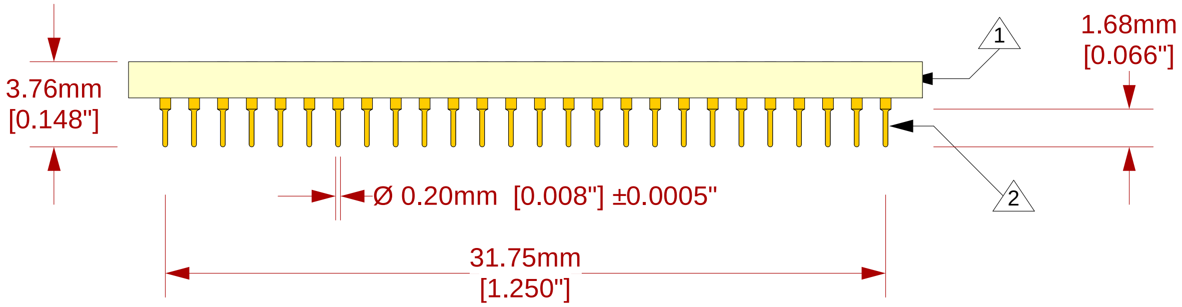
Top View



Side View



△1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]
FR4/G10 or equivalent high temp material.

△2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

Description: Giga-snaP BGA SMT Land Socket
352 position BGA surface mount land pattern to terminal pins (1.27mm [0.050"] centers, 26x26 array)

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

LS-BGA352A-31 Drawing	Status: Released	Scale: 3:1	Rev: A
© 2005 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: S.Natarajan	Date: 6/1/05	
	File: LS-BGA352A-31 Dwg	Modified:	